

Semiconductor Equipment Market Forecasts to 2034 – Global Analysis By Equipment Type (Front-End Equipment, and Back-End Equipment), Process Type (Deposition, Etching, Lithography, Inspection, Metrology, Cleaning, and CMP), Node Size, Application, End User, and By Geography

<https://marketpublishers.com/r/SB4B03A1161DEN.html>

Date: June 2026

Pages: 200

Price: US\$ 4,150.00 (Single User License)

ID: SB4B03A1161DEN

Abstracts

According to Statistics MRC, the Global Semiconductor Equipment Market is accounted for \$143.8 billion in 2026 and is expected to reach \$329.2 billion by 2034 growing at a CAGR of 10.9% during the forecast period. Semiconductor equipment includes machinery used to manufacture integrated circuits and discrete devices. This market encompasses deposition, etching, lithography, ion implantation, metrology, and inspection tools essential for producing chips across all node sizes and applications. Driven by digital transformation, AI computing demand, and the global chip supply chain expansion, semiconductor equipment spending continues reaching record levels. Continuous innovation in process technology and the construction of new fabs worldwide fuel sustained market growth throughout the forecast period.

Market Dynamics:

Driver:

Rising demand for advanced chips across AI, HPC, and automotive sectors

This factor is significantly driving semiconductor equipment purchases as foundries and IDMs expand capacity for compute-intensive applications. Artificial intelligence accelerators, high-performance computing processors, and autonomous driving chips

require leading-edge nodes below 5nm, demanding sophisticated lithography (EUV) and etch equipment. Automotive electrification increases demand for power semiconductors and microcontrollers, driving investment in mature node equipment for 28-90nm processes. Cloud data center expansion and 5G infrastructure build-outs further boost chip consumption. As semiconductor content per electronic device continues rising, chipmakers announce new fab constructions globally, each requiring billions in equipment investment. This diverse demand across node sizes ensures sustained equipment market strength.

Restraint:

Cyclical nature of semiconductor industry and capital expenditure volatility

This factor significantly restrains equipment market predictability as chip demand follows boom-bust cycles tied to global economic conditions, inventory adjustments, and technology transitions. During downturns, chipmakers reduce capital expenditure, delaying fab tool purchases and canceling orders, leading to sharp revenue declines for equipment suppliers. Memory market fluctuations, driven by commodity DRAM and NAND price swings, particularly impact equipment spending as memory manufacturers cut utilization rates. Trade restrictions and geopolitical tensions add uncertainty, with some regions restricting advanced equipment exports. Even during growth periods, procurement cycles are long, with lead times for advanced tools exceeding twelve months. These cyclical patterns create financial planning challenges for equipment manufacturers and their supply chains.

Opportunity:

CHIPS Act and global semiconductor manufacturing incentives

This factor presents substantial opportunities for equipment suppliers as governments worldwide commit billions to domestic chip production. The US CHIPS and Science Act provides direct funding and investment tax credits for fab construction, driving equipment purchases for new facilities. The European Chips Act targets 20% global semiconductor production by 2030, stimulating fab projects across the EU. China, Japan, South Korea, and India have established similar incentive programs. These initiatives not only fund leading-edge capacity but also mature node and specialty process fabs, broadening equipment demand across node categories. Equipment vendors establishing local service and support infrastructure gain competitive advantages. As government-backed fab projects break ground, multi-year equipment

order pipelines strengthen market visibility.

Threat:

Export controls and technology decoupling among major economies

This factor poses a significant threat to semiconductor equipment suppliers as escalating trade restrictions fragment the global market. Restrictions on shipping advanced lithography, etch, and deposition tools to certain countries force equipment vendors to navigate complex compliance regimes, reducing addressable markets. Secondary sanctions risks affect sales to customers that may indirectly supply restricted entities. Technology decoupling leads to parallel supply chain development, duplicating R&D investment without expanding total equipment demand. Chinese domestic equipment suppliers gain share in restricted market segments, challenging incumbent vendors. Export control changes happen with limited notice, creating business continuity risks for long-lead-time equipment orders. These geopolitical pressures reduce total available market and increase operational costs for global equipment suppliers.

Covid-19 Impact:

The COVID-19 pandemic initially disrupted semiconductor equipment markets through factory closures and logistics delays, but ultimately triggered a historic upcycle driven by demand shifts. Lockdowns temporarily halted equipment installation at customer fabs, delaying revenue recognition. However, pandemic-driven digital transformation—remote work, cloud services, gaming, and PC purchases—surged chip demand, leading to global semiconductor shortages. Chipmakers responded by accelerating capacity expansion plans, placing record equipment orders. Supply chain disruptions ironically benefited equipment vendors as customers sought domestic tool sources. Post-pandemic normalization continues, with high utilization rates and new fab construction backlogs sustaining equipment demand. The pandemic permanently elevated baseline semiconductor consumption, establishing a larger equipment market going forward.

The Advanced Nodes segment is expected to be the largest during the forecast period

The Advanced Nodes segment is expected to account for the largest market share during the forecast period, encompassing process technologies from 45nm down to 12nm. This node range serves the majority of semiconductor applications including automotive microcontrollers, connectivity chips (Wi-Fi, Bluetooth), display drivers, and power management ICs. Unlike leading-edge nodes requiring extreme ultraviolet

lithography, advanced nodes use mature 193nm immersion tools with multi-patterning, offering cost-effective performance scaling. Volume production is extremely high due to diverse end-markets. Foundries like TSMC, UMC, and GlobalFoundries generate significant revenue from these nodes. As automotive electronics and IoT device volumes grow, advanced node capacity expands, requiring substantial deposition, etch, and metrology equipment investment, ensuring this segment remains the largest throughout the forecast period.

The Power segment is expected to have the highest CAGR during the forecast period

Over the forecast period, the Power segment is predicted to witness the highest growth rate, fueled by the global transition to electric vehicles, renewable energy systems, and energy-efficient power management. Power semiconductors including IGBTs, MOSFETs, and silicon carbide (SiC) devices require specialized equipment for wide-bandgap material processing, high-energy implantation, and thick metal deposition. EV adoption accelerates demand for power modules in traction inverters, on-board chargers, and DC-DC converters. Solar and wind installations drive power device consumption for grid-tied inverters. Data center efficiency improvements increase power semiconductor content. As silicon carbide and gallium nitride move from niche to mainstream, equipment makers develop dedicated process tools for these materials, with shipments growing at exceptionally high rates compared to mature power device segments.

Region with largest share:

During the forecast period, the Asia Pacific region is expected to hold the largest market share, driven by the concentration of semiconductor manufacturing in Taiwan, South Korea, China, and Japan. Taiwan's TSMC and South Korea's Samsung operate the world's most advanced logic and memory fabs, requiring continuous equipment upgrades. China's massive domestic fab construction program, despite export controls, sustains equipment demand for mature and advanced nodes. Japan maintains strong semiconductor materials and equipment infrastructure. The region accounts for over 75% of global wafer fabrication capacity. Proximity to equipment suppliers including Tokyo Electron, DISCO, and Screen Holdings reduces logistics costs and enables rapid service response. With new fab projects announced across the region annually, Asia Pacific maintains leadership throughout the forecast period.

Region with highest CAGR:

Over the forecast period, the North America region is anticipated to exhibit the highest CAGR, driven by the CHIPS Act incentivizing domestic semiconductor manufacturing and leading-edge research. New fab construction projects announced by Intel, TSMC, Samsung, Texas Instruments, and Micron across Arizona, Ohio, Texas, New York, and Idaho represent tens of billions in equipment investment over the forecast period. The region also hosts major equipment manufacturers including Applied Materials, Lam Research, and KLA, benefiting from local demand. Government-funded R&D for next-generation nodes and advanced packaging creates additional equipment opportunities. While starting from a lower manufacturing base than Asia Pacific, the unprecedented policy-driven capacity expansion delivers the fastest regional growth rate globally.

Key players in the market

Some of the key players in Semiconductor Equipment Market include ASML Holding N.V., Applied Materials Inc., Lam Research Corporation, KLA Corporation, Tokyo Electron Limited, SCREEN Holdings Co. Ltd., Advantest Corporation, Teradyne Inc., Hitachi High-Tech Corporation, Canon Inc., Nikon Corporation, ASM International N.V., Kulicke and Soffa Industries Inc., Disco Corporation, Onto Innovation Inc., Veeco Instruments Inc., Axcelis Technologies Inc., Nordson Corporation, BE Semiconductor Industries N.V., and Cohu Inc.

Key Developments:

In June 2026, Applied Materials India inaugurated an advanced validation facility in Bengaluru capable of processing 300mm wafers, laying the groundwork for a larger, commercially scaled semiconductor research and development center to foster global product innovation.

In June 2026, ASML Holding hosted a technology conference featuring collaborations on the "Terafab" chip fabrication initiative and upgraded its 2026 full-year revenue guidance to between €36 billion and €40 billion, driven by sustained global infrastructure demand for its cutting-edge Extreme Ultraviolet (EUV) lithography systems.

In May 2026, ASML announced a major strategic partnership with Tata Electronics to accelerate the design and localization of the semiconductor manufacturing ecosystem in India, actively supporting upcoming local commercial fabrication plants.

Equipment Types Covered:

Front-End Equipment

Back-End Equipment

Process Types Covered:

Deposition

Etching

Lithography

Inspection

Metrology

Cleaning

CMP

Node Sizes Covered:

Legacy Nodes

Advanced Nodes

Leading-Edge Nodes

Applications Covered:

Logic

Memory

Foundry

Analog

Power

MEMS

CIS

End Users Covered:

Integrated Device Manufacturers

Foundries

OSAT Companies

Research Institutions

Regions Covered:

North America

United States

Canada

Mexico

Europe

United Kingdom

Germany

France

Italy

Spain

Netherlands

Belgium

Sweden

Switzerland

Poland

Rest of Europe

Asia Pacific

China

Japan

India

South Korea

Australia

Indonesia

Thailand

Malaysia

Singapore

Vietnam

Rest of Asia Pacific

South America

Brazil

Argentina

Colombia

Chile

Peru

Rest of South America

Rest of the World (RoW)

Middle East

Saudi Arabia

United Arab Emirates

Qatar

Israel

Rest of Middle East

Africa

South Africa

Egypt

Morocco

Rest of Africa

What our report offers:

- Market share assessments for the regional and country-level segments
- Strategic recommendations for the new entrants
- Covers Market data for the years 2023, 2024, 2025, 2026, 2027, 2028, 2030, 2032 and 2034
- Market Trends (Drivers, Constraints, Opportunities, Threats, Challenges, Investment Opportunities, and recommendations)
- Strategic recommendations in key business segments based on the market estimations
- Competitive landscaping mapping the key common trends
- Company profiling with detailed strategies, financials, and recent developments
- Supply chain trends mapping the latest technological advancements

Free Customization Offerings:

All the customers of this report will be entitled to receive one of the following free customization options:

Company Profiling

Comprehensive profiling of additional market players (up to 3)

SWOT Analysis of key players (up to 3)

Regional Segmentation

Market estimations, Forecasts and CAGR of any prominent country as per the client's interest (Note: Depends on feasibility check)

Competitive Benchmarking

Benchmarking of key players based on product portfolio, geographical presence, and strategic alliances

Contents

1 EXECUTIVE SUMMARY

- 1.1 Market Snapshot and Key Highlights
- 1.2 Growth Drivers, Challenges, and Opportunities
- 1.3 Competitive Landscape Overview
- 1.4 Strategic Insights and Recommendations

2 RESEARCH FRAMEWORK

- 2.1 Study Objectives and Scope
- 2.2 Stakeholder Analysis
- 2.3 Research Assumptions and Limitations
- 2.4 Research Methodology
 - 2.4.1 Data Collection (Primary and Secondary)
 - 2.4.2 Data Modeling and Estimation Techniques
 - 2.4.3 Data Validation and Triangulation
 - 2.4.4 Analytical and Forecasting Approach

3 MARKET DYNAMICS AND TREND ANALYSIS

- 3.1 Market Definition and Structure
- 3.2 Key Market Drivers
- 3.3 Market Restraints and Challenges
- 3.4 Growth Opportunities and Investment Hotspots
- 3.5 Industry Threats and Risk Assessment
- 3.6 Technology and Innovation Landscape
- 3.7 Emerging and High-Growth Markets
- 3.8 Regulatory and Policy Environment
- 3.9 Impact of COVID-19 and Recovery Outlook

4 COMPETITIVE AND STRATEGIC ASSESSMENT

- 4.1 Porter's Five Forces Analysis
 - 4.1.1 Supplier Bargaining Power
 - 4.1.2 Buyer Bargaining Power
 - 4.1.3 Threat of Substitutes
 - 4.1.4 Threat of New Entrants

- 4.1.5 Competitive Rivalry
- 4.2 Market Share Analysis of Key Players
- 4.3 Product Benchmarking and Performance Comparison

5 GLOBAL SEMICONDUCTOR EQUIPMENT MARKET, BY EQUIPMENT TYPE

- 5.1 Front-End Equipment
- 5.2 Back-End Equipment

6 GLOBAL SEMICONDUCTOR EQUIPMENT MARKET, BY PROCESS TYPE

- 6.1 Deposition
- 6.2 Etching
- 6.3 Lithography
- 6.4 Inspection
- 6.5 Metrology
- 6.6 Cleaning
- 6.7 CMP

7 GLOBAL SEMICONDUCTOR EQUIPMENT MARKET, BY NODE SIZE

- 7.1 Legacy Nodes
- 7.2 Advanced Nodes
- 7.3 Leading-Edge Nodes

8 GLOBAL SEMICONDUCTOR EQUIPMENT MARKET, BY APPLICATION

- 8.1 Logic
- 8.2 Memory
- 8.3 Foundry
- 8.4 Analog
- 8.5 Power
- 8.6 MEMS
- 8.7 CIS

9 GLOBAL SEMICONDUCTOR EQUIPMENT MARKET, BY END USER

- 9.1 Integrated Device Manufacturers
- 9.2 Foundries

9.3 OSAT Companies

9.4 Research Institutions

10 GLOBAL SEMICONDUCTOR EQUIPMENT MARKET, BY GEOGRAPHY

10.1 North America

10.1.1 United States

10.1.2 Canada

10.1.3 Mexico

10.2 Europe

10.2.1 United Kingdom

10.2.2 Germany

10.2.3 France

10.2.4 Italy

10.2.5 Spain

10.2.6 Netherlands

10.2.7 Belgium

10.2.8 Sweden

10.2.9 Switzerland

10.2.10 Poland

10.2.11 Rest of Europe

10.3 Asia Pacific

10.3.1 China

10.3.2 Japan

10.3.3 India

10.3.4 South Korea

10.3.5 Australia

10.3.6 Indonesia

10.3.7 Thailand

10.3.8 Malaysia

10.3.9 Singapore

10.3.10 Vietnam

10.3.11 Rest of Asia Pacific

10.4 South America

10.4.1 Brazil

10.4.2 Argentina

10.4.3 Colombia

10.4.4 Chile

10.4.5 Peru

- 10.4.6 Rest of South America
- 10.5 Rest of the World (RoW)
 - 10.5.1 Middle East
 - 10.5.1.1 Saudi Arabia
 - 10.5.1.2 United Arab Emirates
 - 10.5.1.3 Qatar
 - 10.5.1.4 Israel
 - 10.5.1.5 Rest of Middle East
 - 10.5.2 Africa
 - 10.5.2.1 South Africa
 - 10.5.2.2 Egypt
 - 10.5.2.3 Morocco
 - 10.5.2.4 Rest of Africa

11 STRATEGIC MARKET INTELLIGENCE

- 11.1 Industry Value Network and Supply Chain Assessment
- 11.2 White-Space and Opportunity Mapping
- 11.3 Product Evolution and Market Life Cycle Analysis
- 11.4 Channel, Distributor, and Go-to-Market Assessment

12 INDUSTRY DEVELOPMENTS AND STRATEGIC INITIATIVES

- 12.1 Mergers and Acquisitions
- 12.2 Partnerships, Alliances, and Joint Ventures
- 12.3 New Product Launches and Certifications
- 12.4 Capacity Expansion and Investments
- 12.5 Other Strategic Initiatives

13 COMPANY PROFILES

- 13.1 ASML Holding N.V.
- 13.2 Applied Materials Inc.
- 13.3 Lam Research Corporation
- 13.4 KLA Corporation
- 13.5 Tokyo Electron Limited
- 13.6 SCREEN Holdings Co. Ltd.
- 13.7 Advantest Corporation
- 13.8 Teradyne Inc.

- 13.9 Hitachi High-Tech Corporation
- 13.10 Canon Inc.
- 13.11 Nikon Corporation
- 13.12 ASM International N.V.
- 13.13 Kulicke and Soffa Industries Inc.
- 13.14 Disco Corporation
- 13.15 Onto Innovation Inc.
- 13.16 Veeco Instruments Inc.
- 13.17 Axcelis Technologies Inc.
- 13.18 Nordson Corporation
- 13.19 BE Semiconductor Industries N.V.
- 13.20 CoHu Inc.

List Of Tables

LIST OF TABLES

Table 1 Global Semiconductor Equipment Market Outlook, By Region (2023–2034) (\$MN)

Table 2 Global Semiconductor Equipment Market Outlook, By Equipment Type (2023–2034) (\$MN)

Table 3 Global Semiconductor Equipment Market Outlook, By Front-End Equipment (2023–2034) (\$MN)

Table 4 Global Semiconductor Equipment Market Outlook, By Back-End Equipment (2023–2034) (\$MN)

Table 5 Global Semiconductor Equipment Market Outlook, By Process Type (2023–2034) (\$MN)

Table 6 Global Semiconductor Equipment Market Outlook, By Deposition (2023–2034) (\$MN)

Table 7 Global Semiconductor Equipment Market Outlook, By Etching (2023–2034) (\$MN)

Table 8 Global Semiconductor Equipment Market Outlook, By Lithography (2023–2034) (\$MN)

Table 9 Global Semiconductor Equipment Market Outlook, By Inspection (2023–2034) (\$MN)

Table 10 Global Semiconductor Equipment Market Outlook, By Metrology (2023–2034) (\$MN)

Table 11 Global Semiconductor Equipment Market Outlook, By Cleaning (2023–2034) (\$MN)

Table 12 Global Semiconductor Equipment Market Outlook, By CMP (2023–2034) (\$MN)

Table 13 Global Semiconductor Equipment Market Outlook, By Node Size (2023–2034) (\$MN)

Table 14 Global Semiconductor Equipment Market Outlook, By Legacy Nodes (2023–2034) (\$MN)

Table 15 Global Semiconductor Equipment Market Outlook, By Advanced Nodes (2023–2034) (\$MN)

Table 16 Global Semiconductor Equipment Market Outlook, By Leading-Edge Nodes (2023–2034) (\$MN)

Table 17 Global Semiconductor Equipment Market Outlook, By Application (2023–2034) (\$MN)

Table 18 Global Semiconductor Equipment Market Outlook, By Logic (2023–2034)

(\$MN)

Table 19 Global Semiconductor Equipment Market Outlook, By Memory (2023–2034)

(\$MN)

Table 20 Global Semiconductor Equipment Market Outlook, By Foundry (2023–2034)

(\$MN)

Table 21 Global Semiconductor Equipment Market Outlook, By Analog (2023–2034)

(\$MN)

Table 22 Global Semiconductor Equipment Market Outlook, By Power (2023–2034)

(\$MN)

Table 23 Global Semiconductor Equipment Market Outlook, By MEMS (2023–2034)

(\$MN)

Table 24 Global Semiconductor Equipment Market Outlook, By CIS (2023–2034) (\$MN)

Table 25 Global Semiconductor Equipment Market Outlook, By End User (2023–2034)

(\$MN)

Table 26 Global Semiconductor Equipment Market Outlook, By Integrated Device Manufacturers (2023–2034) (\$MN)

Table 27 Global Semiconductor Equipment Market Outlook, By Foundries (2023–2034) (\$MN)

Table 28 Global Semiconductor Equipment Market Outlook, By OSAT Companies (2023–2034) (\$MN)

Table 29 Global Semiconductor Equipment Market Outlook, By Research Institutions (2023–2034) (\$MN)

Note: Tables for North America, Europe, APAC, South America, and Rest of the World (RoW) Regions are also represented in the same manner as above.

I would like to order

Product name: Semiconductor Equipment Market Forecasts to 2034 – Global Analysis By Equipment Type (Front-End Equipment, and Back-End Equipment), Process Type (Deposition, Etching, Lithography, Inspection, Metrology, Cleaning, and CMP), Node Size, Application, End User, and By Geography

Product link: <https://marketpublishers.com/r/SB4B03A1161DEN.html>

Price: US\$ 4,150.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:

info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page <https://marketpublishers.com/r/SB4B03A1161DEN.html>